



3D Printing Technology and Its Applications

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Message from the Guest Editors

Dear Colleagues,

Three-dimensional printing technology, also known as additive manufacturing, permits the construction of various 3D structures by adding material in a “layer-by-layer” manner. Several 3D printing techniques, including polyjet, stereolithography, fused deposition modeling, and selective laser sintering, have been developed to produce acceptable structures for applications in a variety of industries, including electronics, structural materials, and tissue engineering.

With the development of various printable materials such as thermoplastic polymers, photocurable polymers, metals, and composite materials including functional materials such as micro- or nanoparticles, the application range of 3D printing technology is further expanding.

This Special Issue focuses on new approaches in the area of 3D printing technology or their application technologies. Submissions should span all aspects of the development and application of these 3D printing technologies.





Editor-in-Chief

Message from the Editor-in-Chief

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